

SOT96-3

plastic small outline package; 8 leads; body width 3.9 mm;
body thickness 1.47 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-012
Mounting method type	S (surface mount)
Issue date	25-8-2006

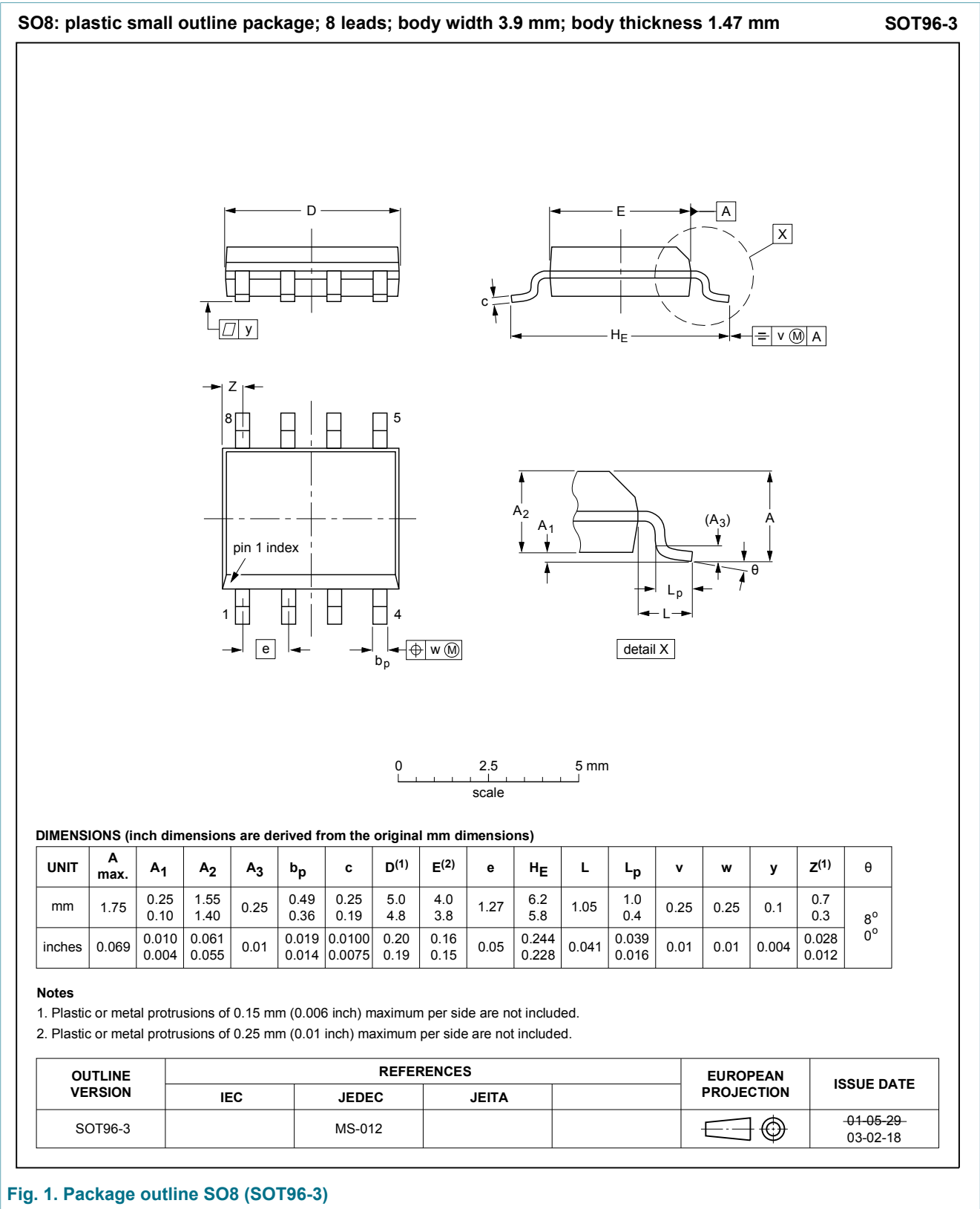
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.8	-	4.9	5	mm
E	package width		3.8	-	3.9	4	mm
A	seated height		[tbd]	-	1.75	1.75	mm
A ₂	package height		1.4	-	1.47	1.55	mm
n ₂	actual quantity of termination		-	-	8	-	



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2. Package outline



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3. Soldering

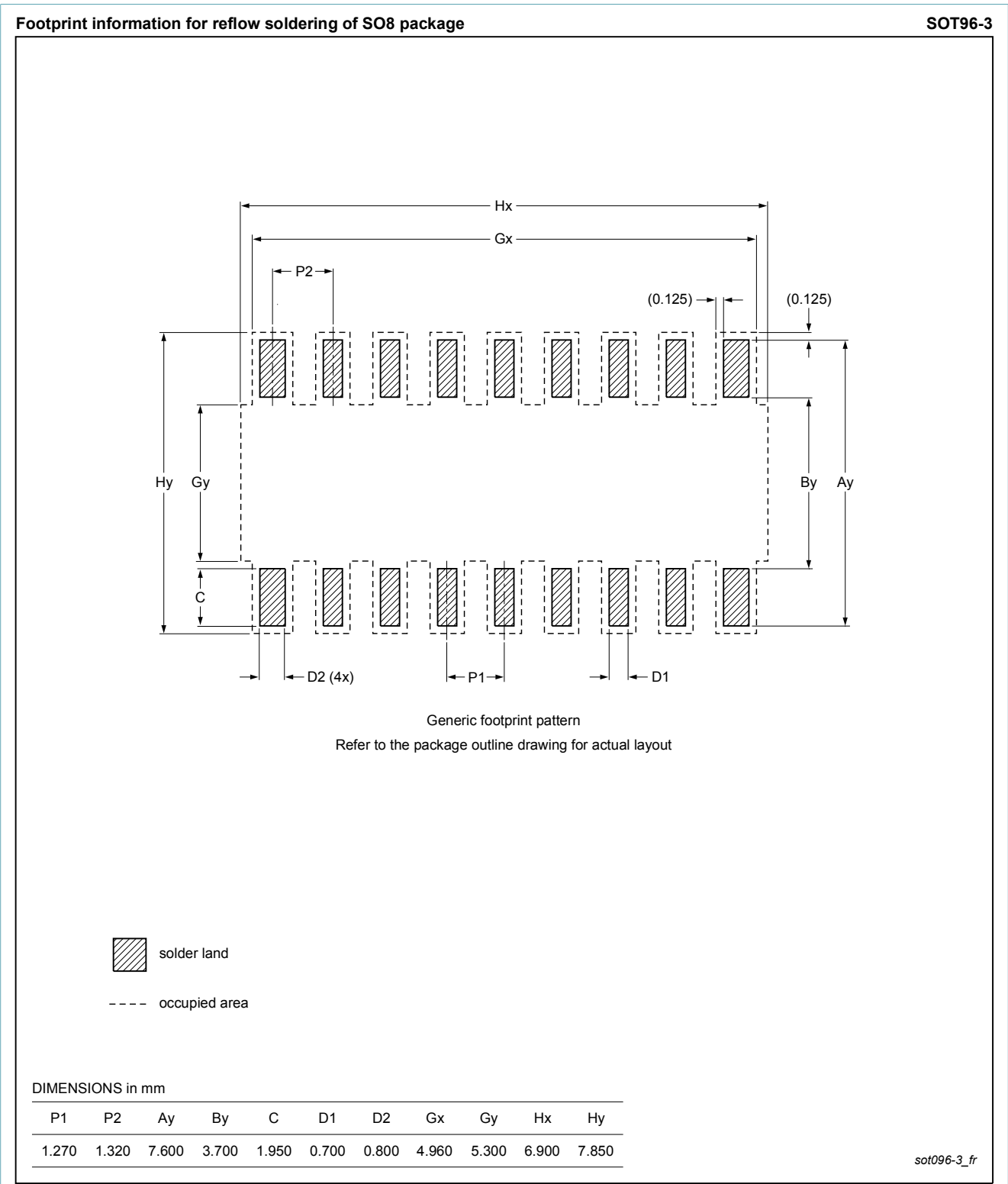


Fig. 2. Reflow soldering footprint for SO8 (SOT96-3)

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4. Legal information

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